

As a below-named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention titled:

## SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING INVERTED SECOND PACKAGE STACKED OVER DIE-UP FLIP-CHIP BALL GRID ARRAY (BGA) PACKAGE

| the specification of which   |   |   |  |   |
|--|---|---|--|---|
| is attached her  | eto.  |   |  |   |
| ⊠ was filed on 08  | October 2003 as Applicati   | ion No. 10/681.747.   |  | •   |
|  | mended on ( <i>if applicable</i>  |   |  |   |
| and was a  | mended on (ii applicable  | <del>5</del> ).   |  |   |
|  | nat I have reviewed and claims, as amended by any   |   |  | bove-identified   |
| application in accordance value individual associated good faith in dealing with that individual to be material to particular to particular individual indi | e duty to disclose inform with Title 37, Code of Federal with the filing and prosect ne Office, which includes a late of patentability as define attentability is deemed to be sued in a patent was cited all) and 1.98." | ral Regulations, § 1.56(a<br>sution of a patent applica<br>duty to disclose to the<br>ed in this sectionThe<br>be satisfied if all inform | a) which states in<br>ation has a duty<br>Office all inform<br>duty to disclose<br>nation known to | n relevant part<br>of candor and<br>ation known to<br>all information<br>be material to |
| application(s) for patent o  | eign priority benefits unde<br>r inventor's certificate as<br>nt or inventor's certificate of<br>y is claimed:  | indicated below and h   | ave also identif   | ied below any   |
| Prior Foreign Application(s)   |   |   | Priority Claimed   |   |
| (Number) (Countr   | y) (Day/Month/Year Filed  | 1   | ☐ Yes  | ☐ No  |
| (Mainber) (Count   | y) (Day/Month/Teal Tiled  | )   |  |   |
| (Number) (Countr   | y) (Day/Month/Year Filed  | )   | . L Yes  | ☐ No  |
| application(s), and under  | l, I acknowledge the duty t<br>ns, § 1.56(a) which occurre  | Code, § 119(e) of a t matter of each of the of e manner provided by to disclose material informed between the filing date.                | ny United Stat<br>claims of this ap<br>the first paragra<br>rmation as defir                       | es provisiona<br>plication is no<br>uph of Title 35<br>ned in Title 37                  |
| 60/417,277   | 8 October 2002  | Abandoned   |  |   |
| (Application No.)  | Filing Date)  | (Status: Patented,  | Pending, Aband   | ioned)  |
| 60/460,541   | 04 April 2003   | Pending   | <b>J</b> .   | •   |
| (Application No.)  | (Filing Date)   | (Status: Patented   | Pending Ahang  | loned)  |

|  | Trademark Office conn  | Pending (Status: Patented, Pending, Abandoned) for agent(s) to prosecute this application and transacted therewith, and to file, prosecute and to transactins directed to said invention:   |
|--|--|---|
| Mark A.<br>Ernest  | Haynes Reg. No. 1. Beffel, Jr. Reg. No. 1. | No. 30,846<br>No. 43,489<br>No. 31,454<br>No. 29,719<br>No. 33,407  |
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| Direct all telephone calls to _E   | Bill Kennedy at (650) 71   | 2-0340.   |
| statements made on informat made with the knowledge th   | ion and belief are believ<br>at willful false stateme<br>Title 18, United States   | herein of my own knowledge are true and that a yed to be true; and further that these statements were nts and the like so made are punishable by fine of Code, § 1001 and that such willful false statement atent issued thereon. |
| Full name of <b>sole</b> or <b>first</b> inventor:   | Marcos Karnezos  |   |
| Inventor's signature:  | Margo  | 1/23/04   |
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